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TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

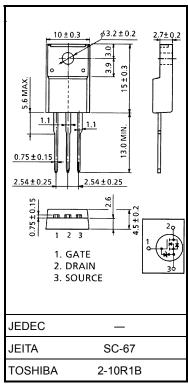
2SK2717

DC-DC Converter and Motor Drive Applications

- Low drain-source ON resistance $: R_{DS} (ON) = 2.3 \Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 4.4 \text{ S} (\text{typ.})$ •
- Low leakage current : $I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 720 \ V)$
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	900	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	900	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	۱ _D	5	А	
	Pulse (Note 1)	I _{DP}	15	A	
Drain power dissipation	n (Tc = 25°C)	PD	45	W	
Single pulse avalanche energy (Note 2)		E _{AS}	595	mJ	
Avalanche current		I _{AR}	5	А	
Repetitive avalanche energy (Note 3)		E _{AR}	4.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 43.6 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm

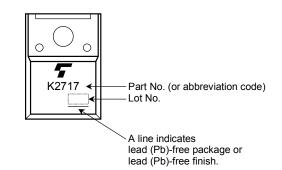
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V		—	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_		V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 3.0 A	_	2.3	2.5	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 20 V, I _D = 3.0 A	1.1	4.4	_	S
Input capacitance	ce	C _{iss}			1200	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		20	_	pF
Output capacitance		C _{oss}			120	—	
Switching time	Rise time	tr	$V_{GS} \stackrel{10V}{}_{0V} \prod \qquad I_{D} = 3A \qquad V_{out}$ $V_{GS} \stackrel{10V}{}_{0V} \prod \qquad R_{L} = 66.7\Omega$ $V_{DD} = 200V$	_	40	_	
	Turn-on time	t _{on}		_	90	_	
	Fall time	t _f		_	60	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w =10µs	_	200	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	45	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 5 A	_	25	_	nC
Gate-drain ("miller") Charge		Q _{gd}]		20	—	

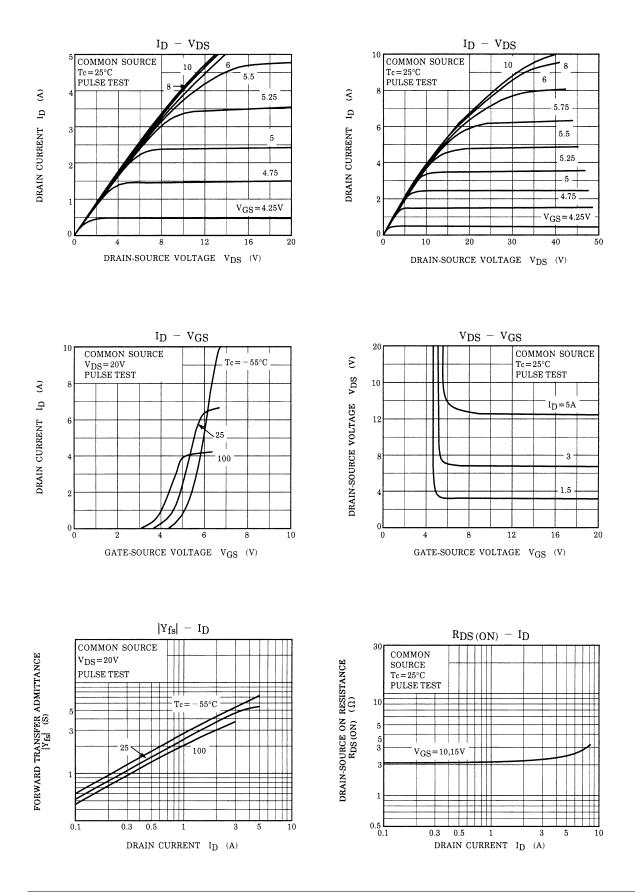
Source–Drain Ratings and Characteristics (Ta = 25°C)

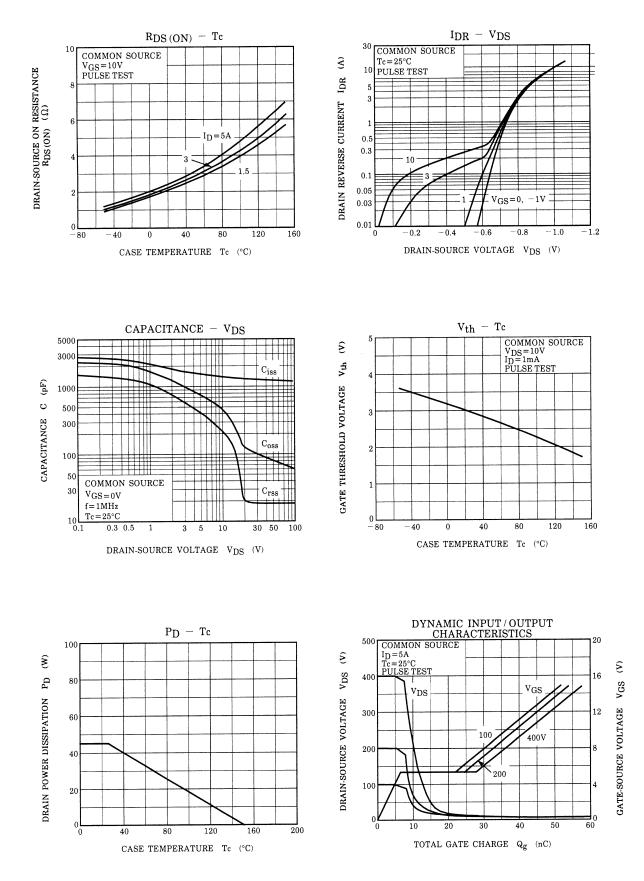
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	5	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	15	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V			-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs		1300		ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	11	_	μC

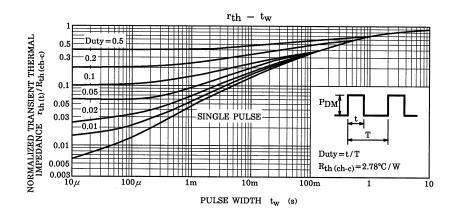
Marking

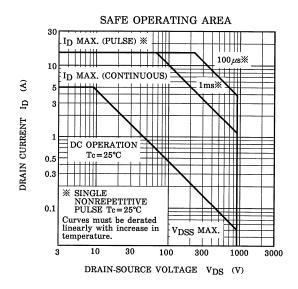


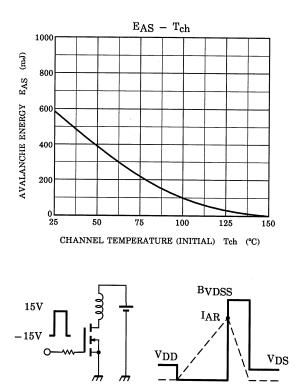
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TEST CIRCUIT WAVE FORM

$$\begin{array}{l} \mathrm{RG} = 25 \ \Omega \\ \mathrm{VDD} = 90 \ \mathrm{V}, \ \mathrm{L} = 43.6 \ \mathrm{mH} \end{array} \qquad \qquad \\ \mathrm{EAS} = \frac{1}{2} \cdot \mathrm{L} \cdot \mathrm{I}^2 \cdot \left(\frac{\mathrm{BVDSS}}{\mathrm{BVDSS} - \mathrm{VDD}} \right) \end{array}$$

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